

### **AMENDMENTS TO THE CLAIMS**

*The listing of claims will replace all prior versions and listings of claims in the application:*

#### **Listing of Claims:**

1.     **(Currently Amended)**     An optical transceiver comprising:  
a housing;  
a circuit board configured to be received within the housing;  
an optical subassembly having a can and a barrel, the optical subassembly mechanically supported on the housing and electrically coupled to the circuit board; and  
a heat wick thermally coupled between the optical assembly and the housing,  
wherein the heat wick includes a sleeve and a flange, the sleeve configured to fit over the can of the optical subassembly and the flange configured to be coupled with the housing such that the can of the optical subassembly is thermally coupled directly to the housing.
2.     **(Original)**     The optical transceiver of claim 1, wherein the optical subassembly is mechanically supported on the housing independently of the connection of the heat wick between the optical subassembly and the housing.
3.     **(Original)**     The optical transceiver of claim 2, wherein the optical subassembly is mechanically supported by a nest on the housing.
4.     **Cancelled**
5.     **Cancelled**
6.     **Cancelled**

7. **(Currently Amended)** The optical transceiver of claim [[4]] 1, wherein the housing includes a slot through which the flange of the heat wick extends, and wherein the flange is bent over onto a surface of the housing to thermally couple the flange to the housing.

8. **(Original)** The optical transceiver of claim 1 further comprising a second optical subassembly, wherein the optical subassembly includes an optical emitter for receiving electrical signals and producing responsive optical signals and wherein the second optical subassembly functions includes an optical receiver for receiving optical signals and producing responsive electrical signals.

9. **(Original)** The optical transceiver of claim 8 further including a second heat wick, wherein the second optical subassembly has a can and a barrel and wherein the second heat wick is thermally coupled between the can of the second optical assembly and the housing.

10. **(Original)** The optical transceiver of claim 8, wherein the optical receiver is a photodiode and wherein the optical emitter is a laser.

11. **(Original)** The optical transceiver of claim 1, wherein the heat wick is made of copper.

12. **(Original)** The optical transceiver of claim 1, wherein the heat wick is coupled to the can of the optical subassembly using conductive epoxy.

13. **(Original)** The optical transceiver of claim 1, wherein the heat wick is coupled to the can of the optical subassembly using silver-filled conductive epoxy.

14. **(Original)** The optical transceiver of claim 1, wherein the optical subassembly has a back surface, wherein subassembly leads project out from the back surface and are

electrically coupled to the circuit board and wherein the heat wick is coupled to the back surface of the optical subassembly.

15. **(Original)** The optical transceiver of claim 1, wherein the transceiver is a small form factor transceiver.

16. **(Currently Amended)** A method for providing heat sinking in an optical transceiver, comprising the steps:

providing a transceiver housing; providing a circuit board;

electrically coupling an optical subassembly to the circuit board;

mechanically coupling the optical subassembly and the circuit board to the transceiver housing;

thermally coupling the optical subassembly to the transceiver housing using a heat wick configured to contact the optical subassembly and the transceiver housing, wherein thermally coupling the optical subassembly to the transceiver housing using a heat wick includes mounting the heat wick onto the optical subassembly after the optical subassembly has been mechanically coupled to the transceiver housing and then bending the heat wick over onto a portion of the transceiver housing to thermally couple the optical subassembly an the transceiver housing.

17. **Cancelled**

18. **(Original)** The method of claim 16, wherein the optical subassembly is mechanically supported on the transceiver housing independently of the connection of the heat wick between the optical subassembly and the transceiver housing.

19. **Cancelled**

20. **Cancelled**

21. **(New)** An optical transceiver comprising:
- a housing;
  - a circuit board configured to be received within the housing;
  - an optical subassembly having a can and a barrel, the optical subassembly mechanically supported on the housing and electrically coupled to the circuit board; and
  - a heat wick thermally coupled between the optical assembly and the housing, wherein the heat wick includes a sleeve and a flange, the sleeve configured to fit over the can of the optical subassembly and the flange configured to be coupled with the housing such that the can of the optical subassembly is thermally coupled directly to the housing, wherein the housing includes a recess into which the flange is configured to be received..
22. **(New)** The optical transceiver of claim 21, further including a cover configured to fit over the flange and within the recess thereby retaining the flange within the recess.